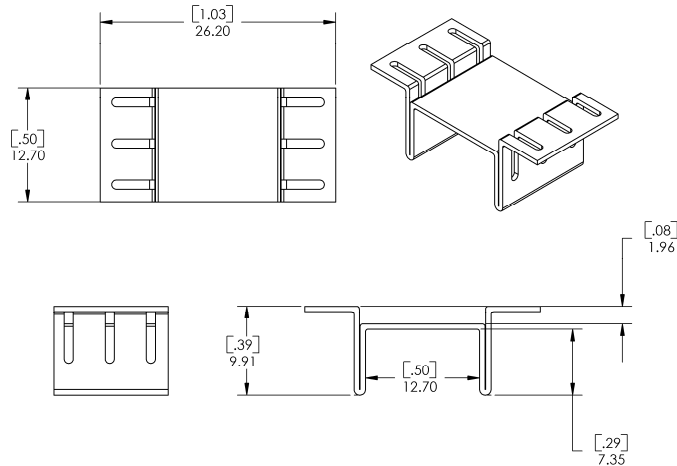
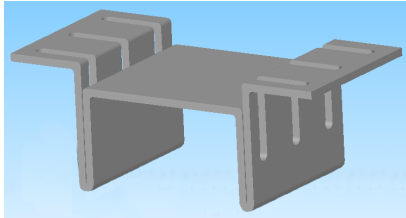


Board Level Heat Sinks



ThermaFlo

P/N: 832700T00000 & 8327TRT00000



PRODUCT SPECIFICATIONS

- Devices: D2 PAK, TO-263
- Size: 26.2 x 12.7 x 9.9 mm
- Copper, 0.6 mm Thick
- Type: Stamped
- PCB Mounting: Surface Mount Technology
- Finish: Tin Plate
- Package: Bulk or Tape & Reel

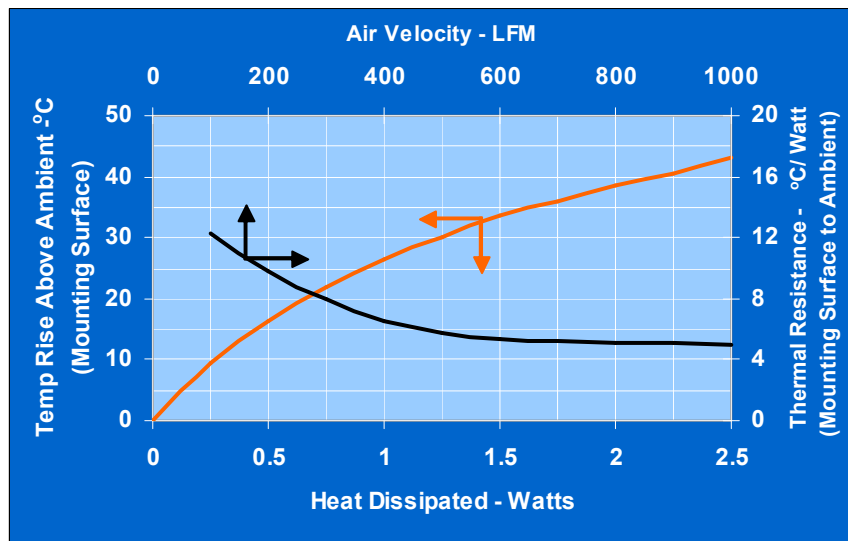
FEATURES & BENEFITS

- No Hardware Device Attachment
- Direct SMT Contact to PCB
- Solderable Legs
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Body Configurations
- Contact Applications Engineering



D2 PAK, TO-263

Part Number	Packaging	Notes
832700T00000	Bulk	
8327TRT00000	Tape & Reel	Contact Factory for Tape and Reel Specs

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